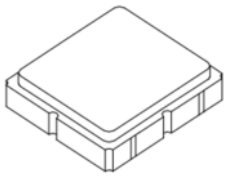
RFM
A BRAND OF AKOUSTIS

RoHS compliant

SF2008D

930.5 MHz SAW Filter

- ***RF Filter for Pager Applications***
- ***High Rejection Out of Band***
- ***Complies with Directive 2002/95/EC (RoHS)***
- ***Moisture Sensitivity Level: 1***



SM3838-6

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	0	dBm
Maximum DC Voltage Between Any Two Terminals	30	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_C			930.5		MHz
Passband Insertion Loss, 928.5 to 932.5 MHz	IL_{MAX}				4.5	dB
Passband Amplitude Ripple, 928.5 to 932.5 MHz					2.0	dB_{P-P}
Rejection Referenced to IL_{MAX}						
400 to 880 MHz			35			dB
884.8 to 890.2 MHz			40			
906.8 to 911.2 MHz			30			
980 to 1300 MHz			35			
Operating Temperature Range	T_A		-20		+70	°C
Input Impedance at f_C	50 - j57 ohm					
Output Impedance at f_C	50 - j57 ohm					

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	455, YWWS

Electrical Connections

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

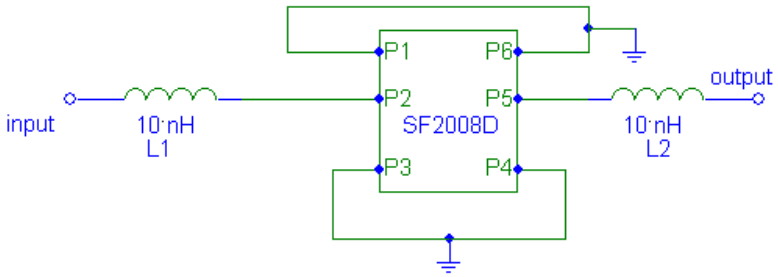
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

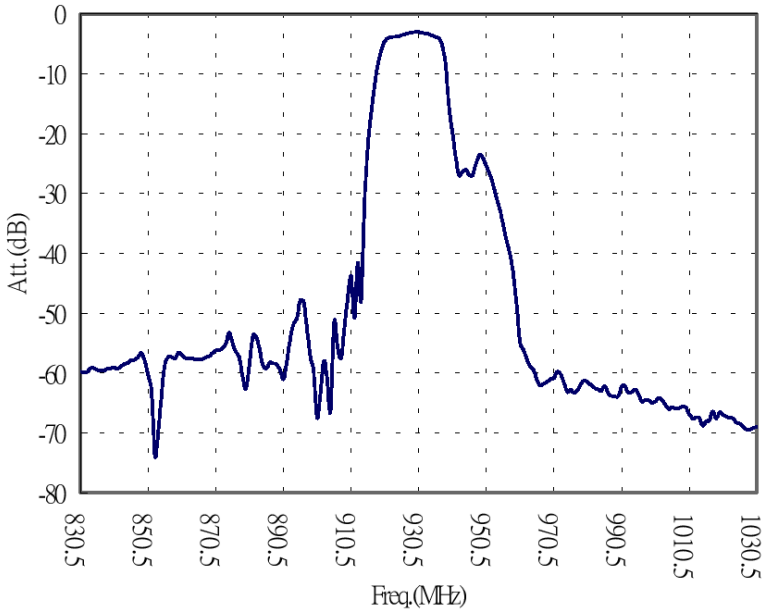
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

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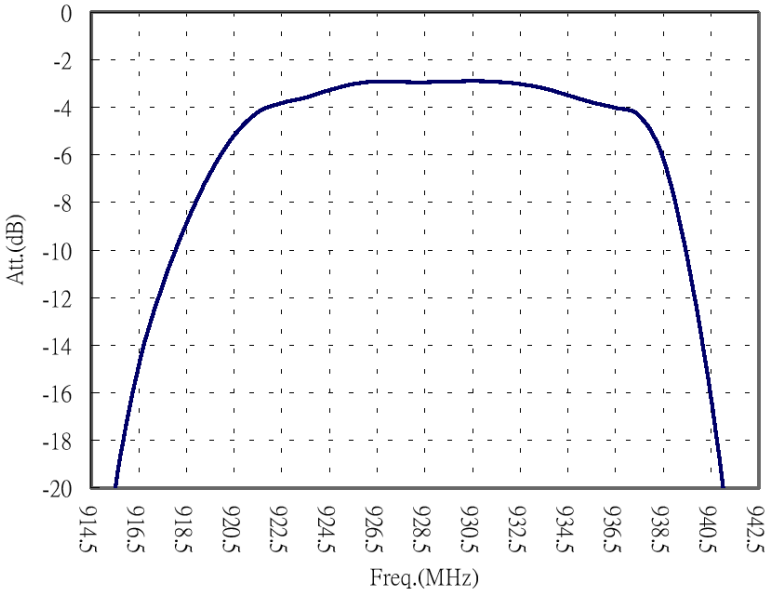
Matching Circuit



S21 Wide Span



S21 Narrow Span

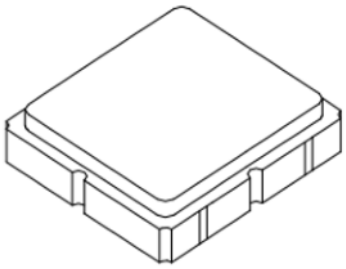


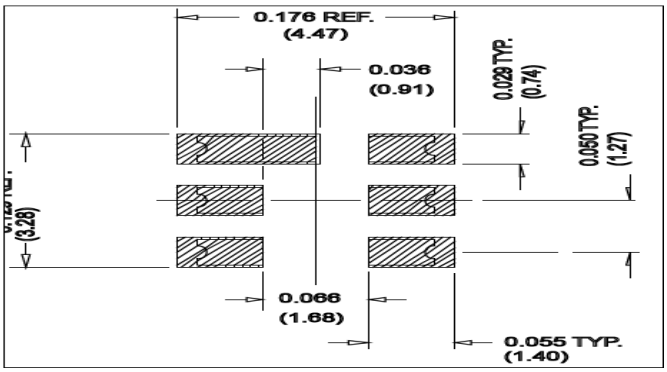
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SM3838-6 Case

6-Terminal Ceramic Surface-Mount Case

3.8 X 3.8 mm Nominal Footprint





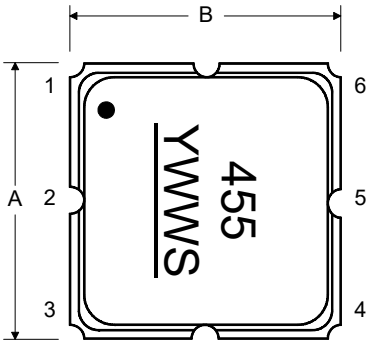
PCB Footprint

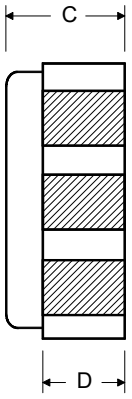
Case Dimensions						
Dimension	**mm**			**Inches**		
	Min	**Nom**	**Max**	**Min**	**Nom**	**Max**
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.30	1.50	1.70	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.75	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

Electrical Connections		
Connection		**Terminals**
Port 1	Single-ended Input	2
Port 2	Single-ended Output	5
	Ground	All others
Single-ended Operation Only		
Dot indicates Pin 1		

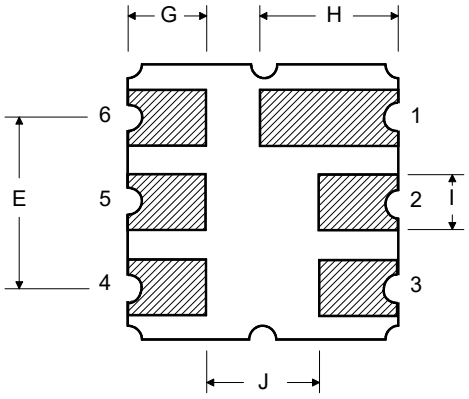
Materials	
Solder Pad Plating	0.3 to 1.0 µm Gold over 1.27 to 8.89 µm Nickel
Lid Plating	2.0 to 3.0 µm Nickel
Body	Al_2O_3 Ceramic

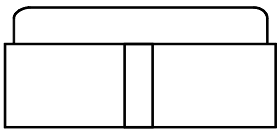
TOP VIEW





BOTTOM VIEW

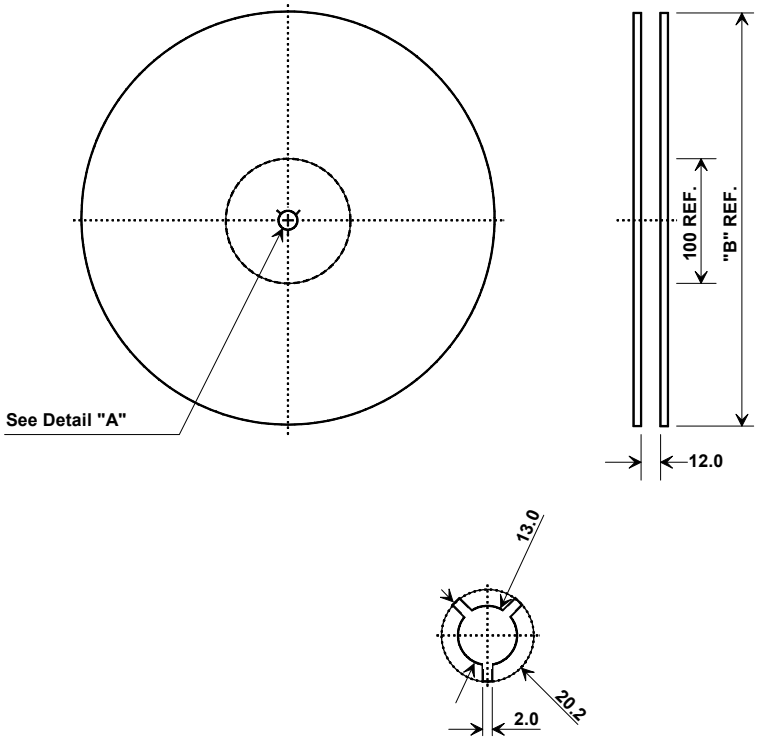




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Tape and Reel Specifications

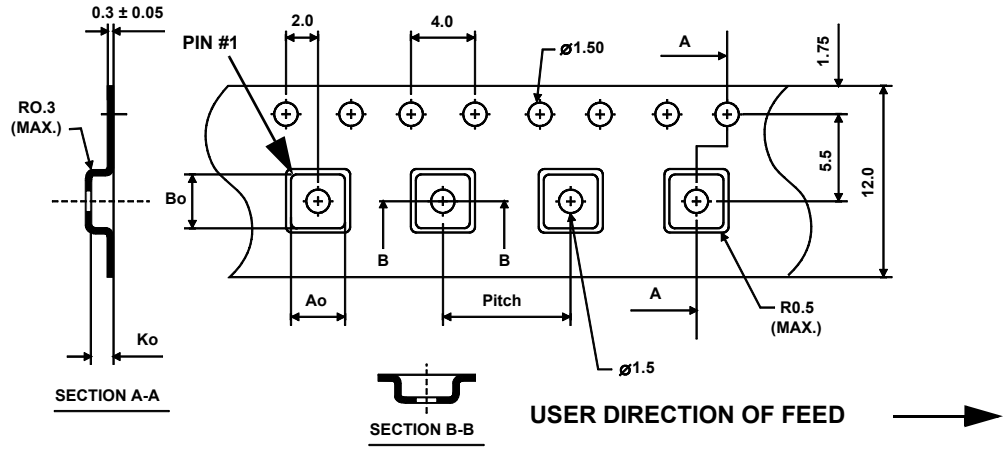
Tape and Reel Standard per ANSI/EIA-481



"B " Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	1000
13	330	3000

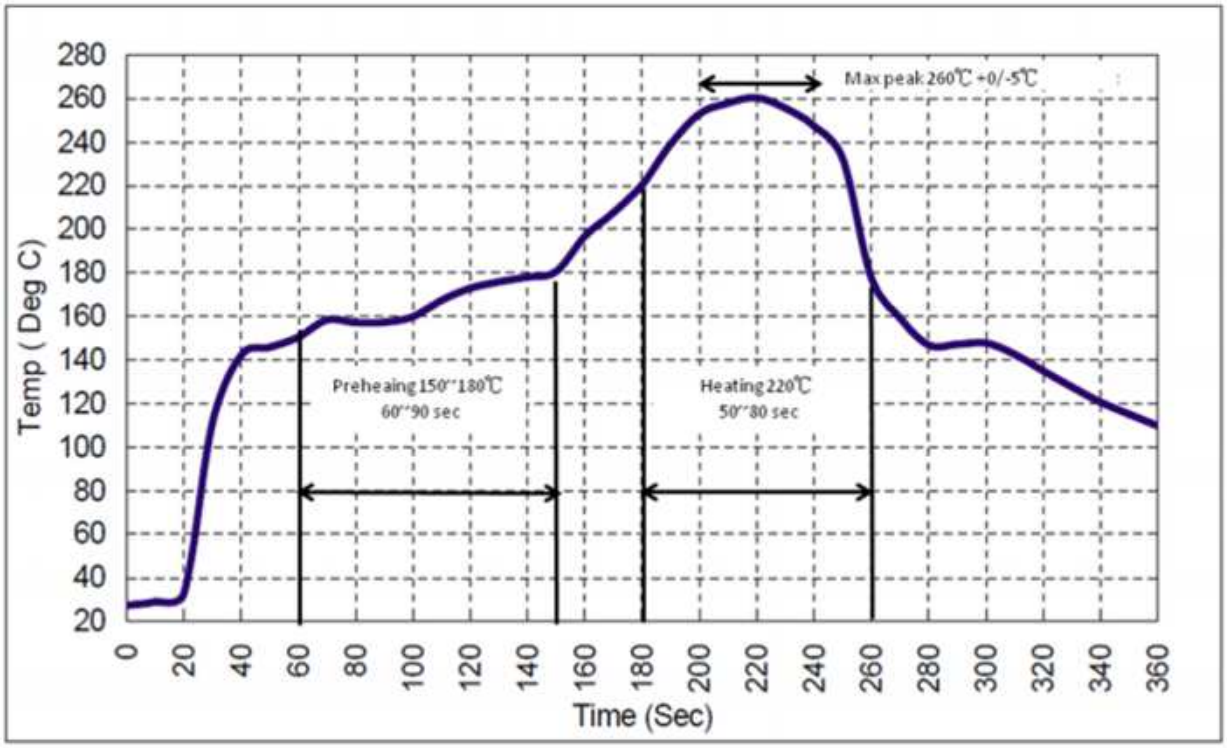
COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C+0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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